

IN THE CLAIMS:

Please amend the claims as follows:

1. (Previously Presented) A laser-markable tape for marking a semiconductor device comprising:

a tape comprising a flexible film material; and

a multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components, said electromagnetic radiation-curable components providing a laser-markable surface upon exposure to an electromagnetic radiation source; and

a second adhesive layer disposed between said tape and said first outermost adhesive layer.

2. (Previously Presented) The laser-markable tape of claim 1, wherein said laser-markable tape is adhered to at least a portion of a surface of a bare semiconductor die.

3. (Previously Presented) The laser-markable tape of claim 2, wherein said laser-markable tape is adhered to a bare semiconductor die surface subjected to a backgrinding process.

4. (Previously Presented) The laser-markable tape of claim 2, wherein said first outermost adhesive layer is cured upon exposure to said electromagnetic radiation source to thereby attach said first outermost adhesive layer to said at least a portion of said surface of said bare semiconductor die.

5. (Previously Presented) The laser-markable tape of claim 4, wherein said curing of said first outermost adhesive layer results in a loss of adhesion between said first outermost adhesive layer and said second adhesive layer.

6. (Previously Presented) The laser-markable tape of claim 4, wherein said curing of said first outermost adhesive layer forms a substantially homogenous surface over said at least a portion of said surface of said bare semiconductor die suitable for laser marking.

7. (Previously Presented) The laser-markable tape of claim 3, wherein said second adhesive layer is cured by exposure to an electromagnetic radiation source.

8. (Previously Presented) The laser-markable tape of claim 1, wherein said tape comprises a flexible film material having translucent properties.

9. (Previously Presented) A tape for use in the laser marking of a semiconductor device comprising:

a flexible film material; and

a multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a laser-markable surface upon exposure thereof to electromagnetic radiation; and
a second adhesive layer disposed between said flexible film material and said first outermost adhesive layer.

10. (Original) The tape of claim 9, wherein said tape includes a tape for adhering to at least a portion of a surface of a bare semiconductor die.

11. (Previously Presented) The tape of claim 10, wherein said tape includes a tape for adhering to said portion of said surface of said bare semiconductor die after backgrinding of said portion of said surface of said bare semiconductor die.

12. (Previously Presented) The tape of claim 10, wherein said first outermost adhesive layer includes a first outermost adhesive layer for curing upon exposure to a source of electromagnetic radiation for attaching said first outermost adhesive layer to said at least a portion of said surface of said bare semiconductor die.

13. (Original) The tape of claim 12, wherein said curing of said first outermost adhesive layer provides a loss of adhesion between said first outermost adhesive layer and said second adhesive layer.

14. (Previously Presented) The tape of claim 12, wherein said curing of said first outermost adhesive layer forms a substantially homogenous surface over said at least a portion of said surface of said bare semiconductor die suitable for providing a mark by laser marking.

15. (Previously Presented) The tape of claim 11, wherein said second adhesive layer is cured by exposure to electromagnetic radiation.

16. (Previously Presented) The tape of claim 9, wherein said flexible film material comprises a flexible film material having translucent properties.

17. (Previously Presented) A tape for use in the marking of a semiconductor device comprising:

film material; and

at least two layers of adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic

radiation-curable components for providing a mark on a surface upon exposure thereof to electromagnetic radiation; and

a second adhesive layer disposed between said film material and said first outermost adhesive layer.

18. (Original) The tape of claim 17, wherein said tape includes a tape for adhering to at least a portion of a surface of a bare semiconductor die.

19. (Previously Presented) The tape of claim 18, wherein said tape includes a tape for adhering to said portion of said surface of said bare semiconductor die after a backgrinding process.

20. (Previously Presented) The tape of claim 18, wherein said first outermost adhesive layer includes a first outermost adhesive layer for curing upon exposure to electromagnetic radiation for attaching said first outermost adhesive layer to said at least a portion of said surface of said bare semiconductor die.

21. (Original) The tape of claim 20, wherein said curing of said first outermost adhesive layer provides a loss of adhesion between said first outermost adhesive layer and said second adhesive layer.

22. (Previously Presented) The tape of claim 20, wherein said curing of said first outermost adhesive layer forms a substantially homogenous surface over said at least said portion of said surface of a bare semiconductor die suitable for laser marking for forming a mark on said surface of said bare semiconductor die.

23. (Previously Presented) The tape of claim 19, wherein said second adhesive layer includes a layer cured by exposure to electromagnetic radiation.

24. (Previously Presented) The tape of claim 17, wherein said film material comprises a film material having translucent properties.